

Fig 1

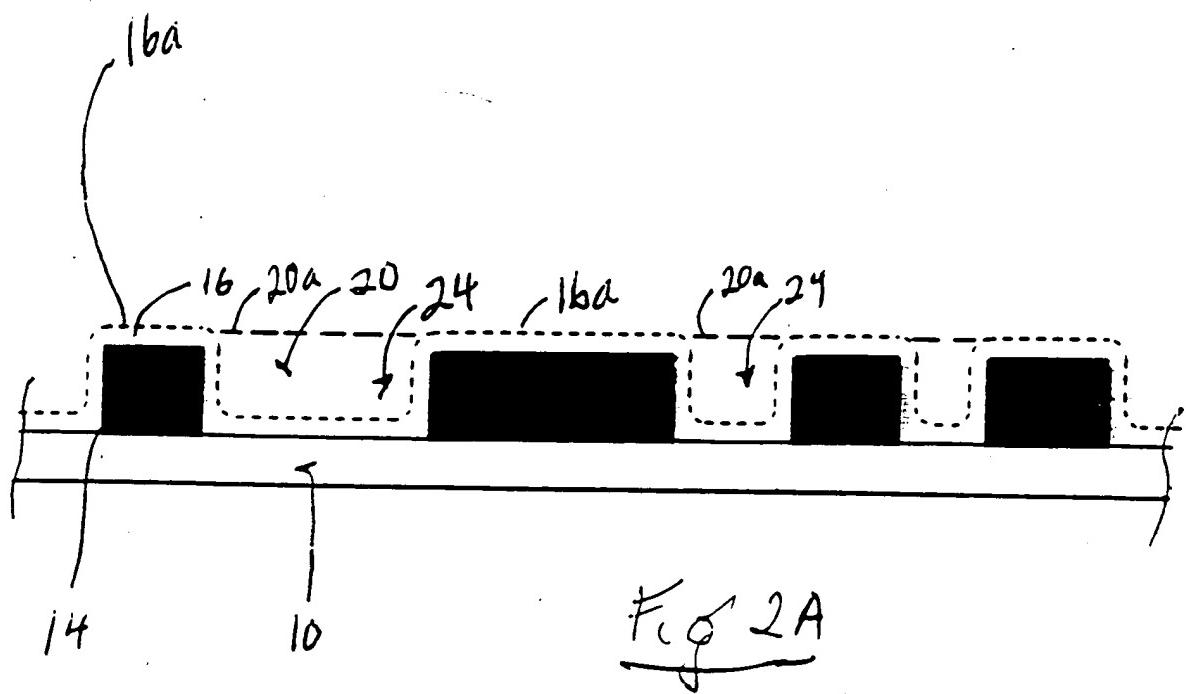


Fig 2A

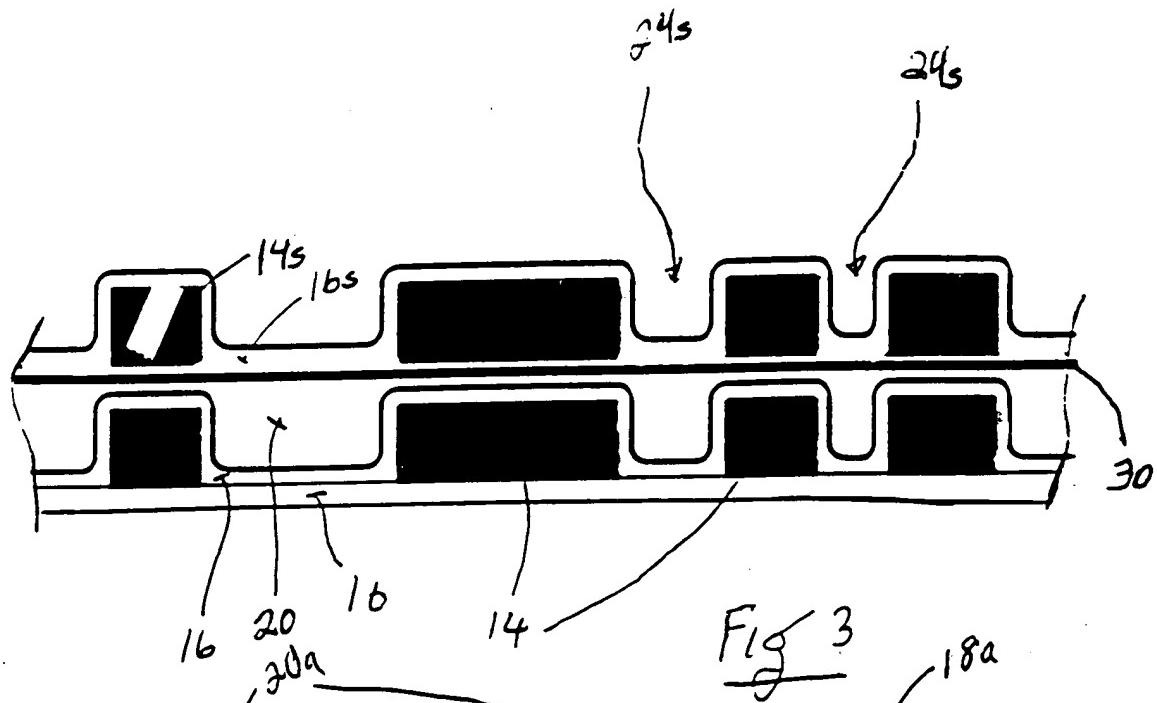
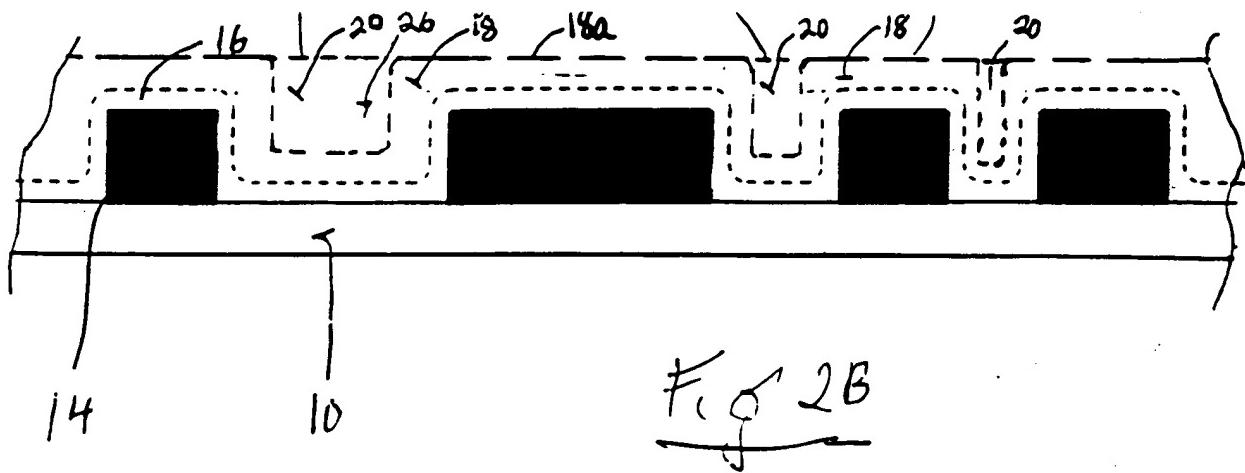


Figure : After deposition of gapfilling polymer and CMP



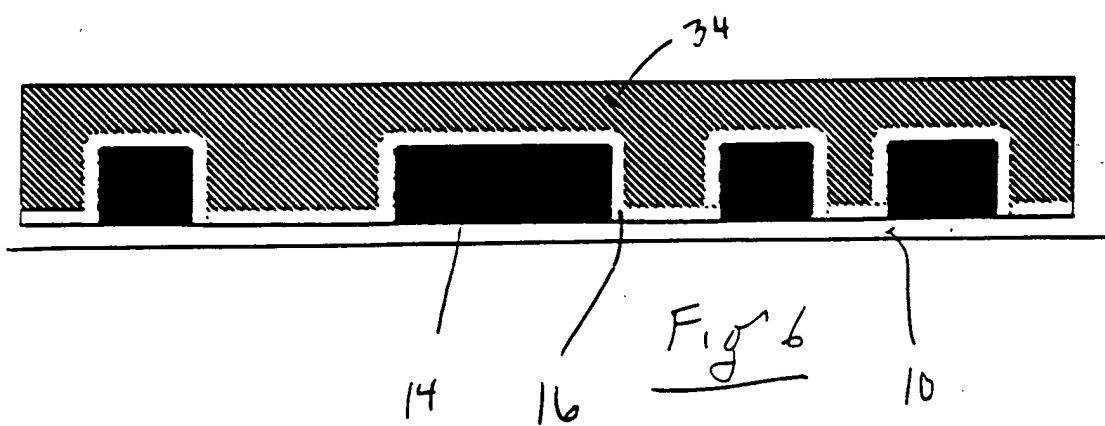
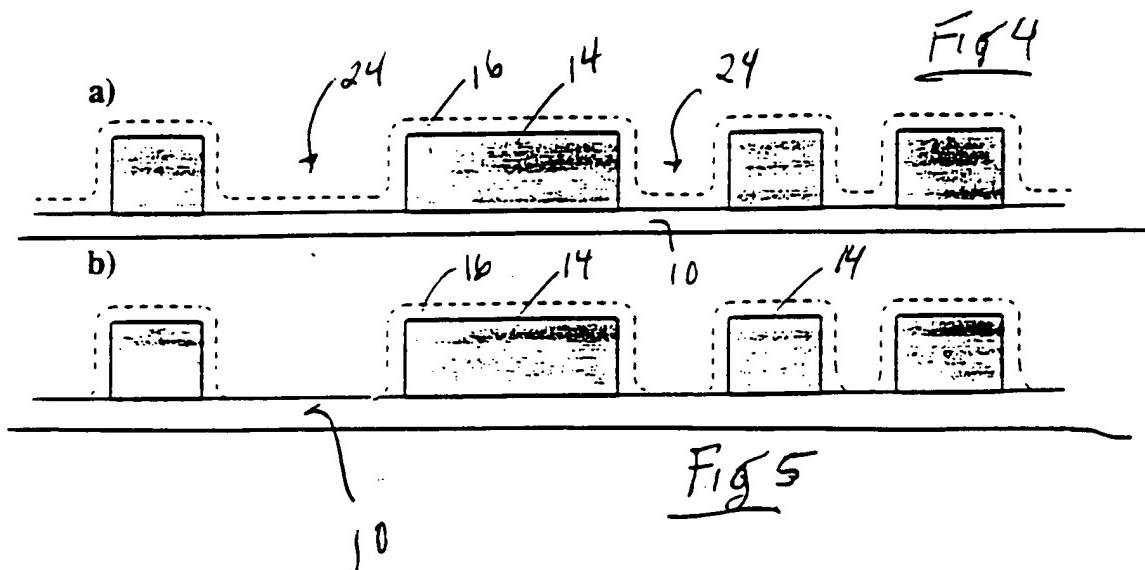


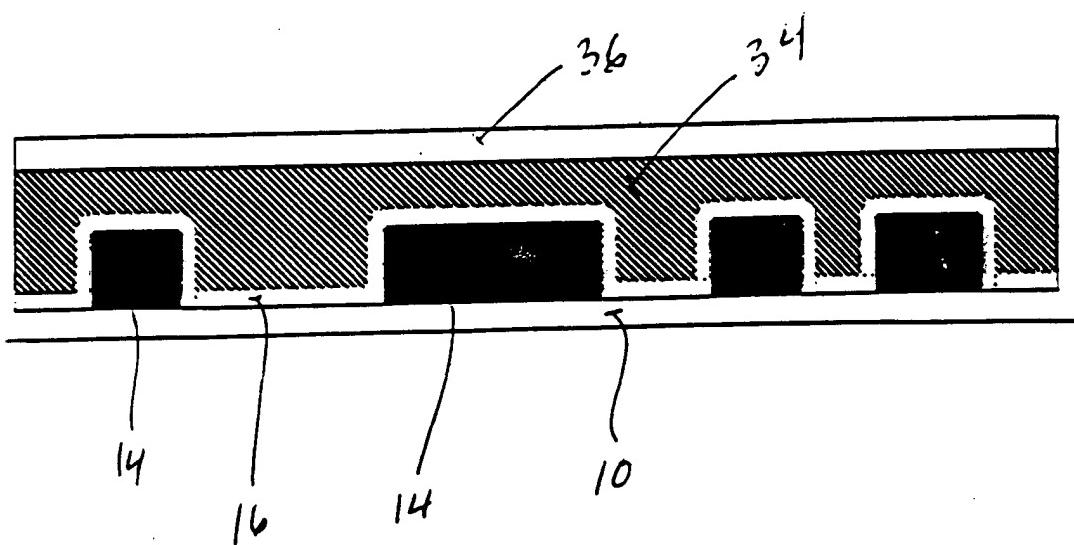
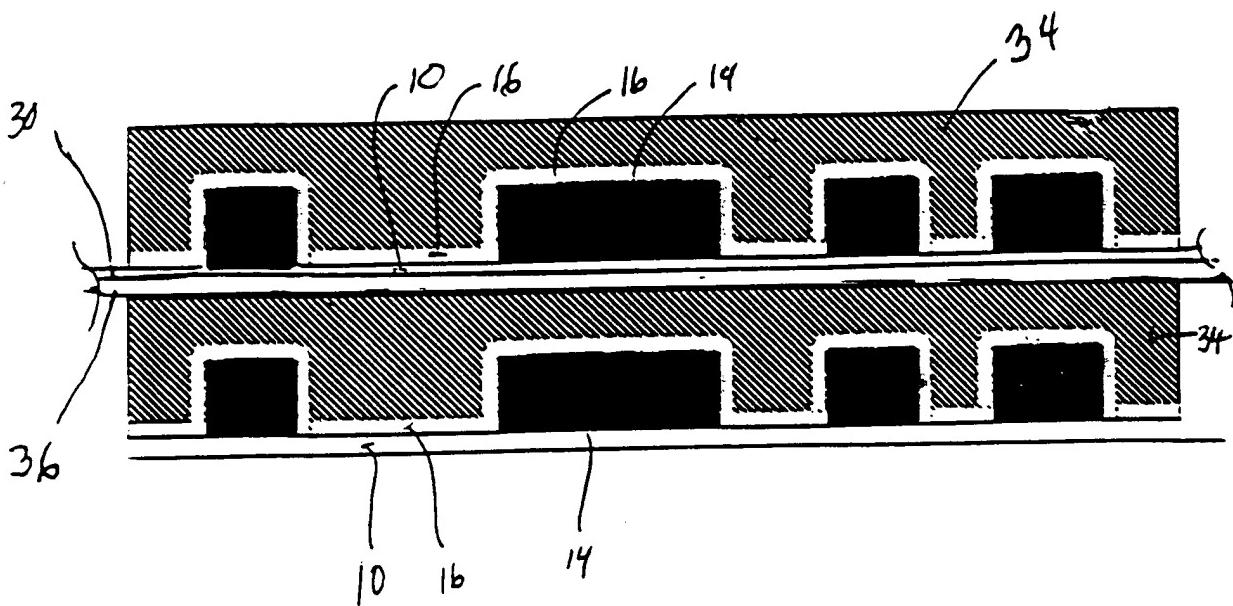
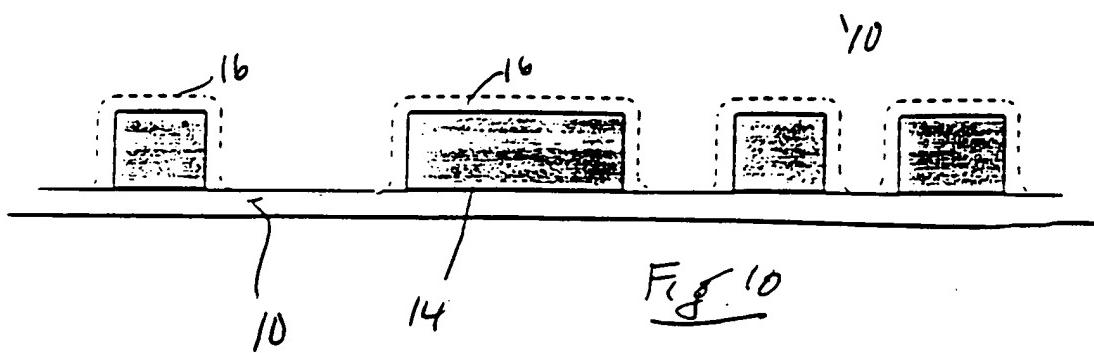
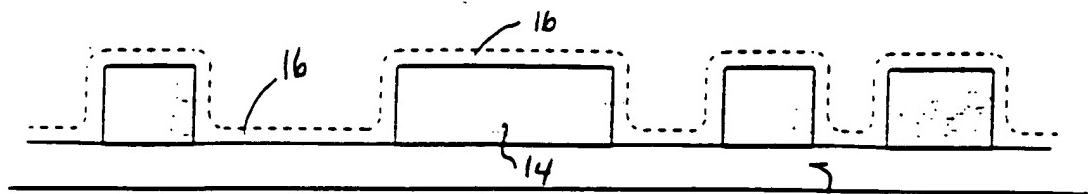
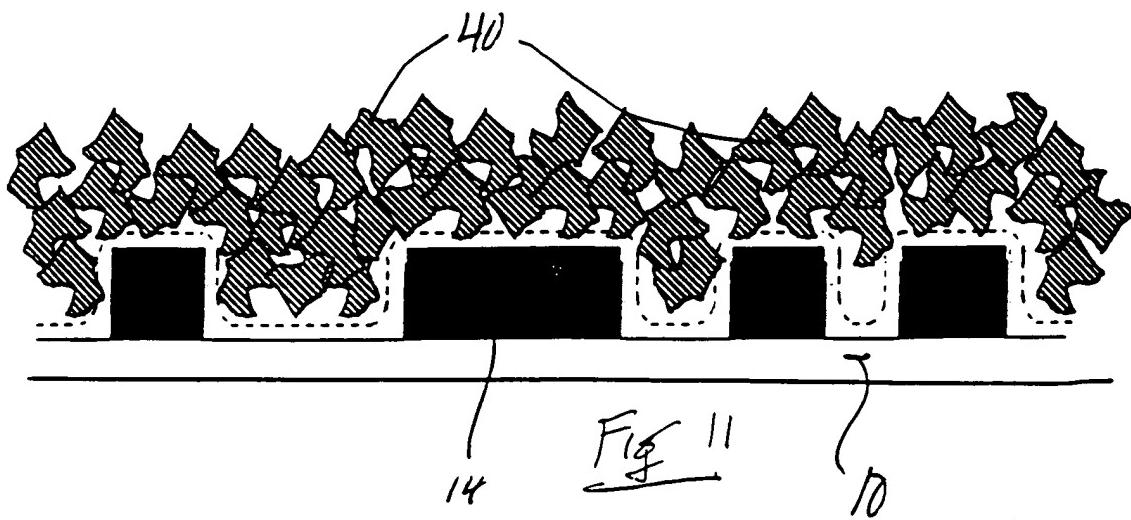
Fig 7Fig 8

Fig 9Fig 10Fig 11

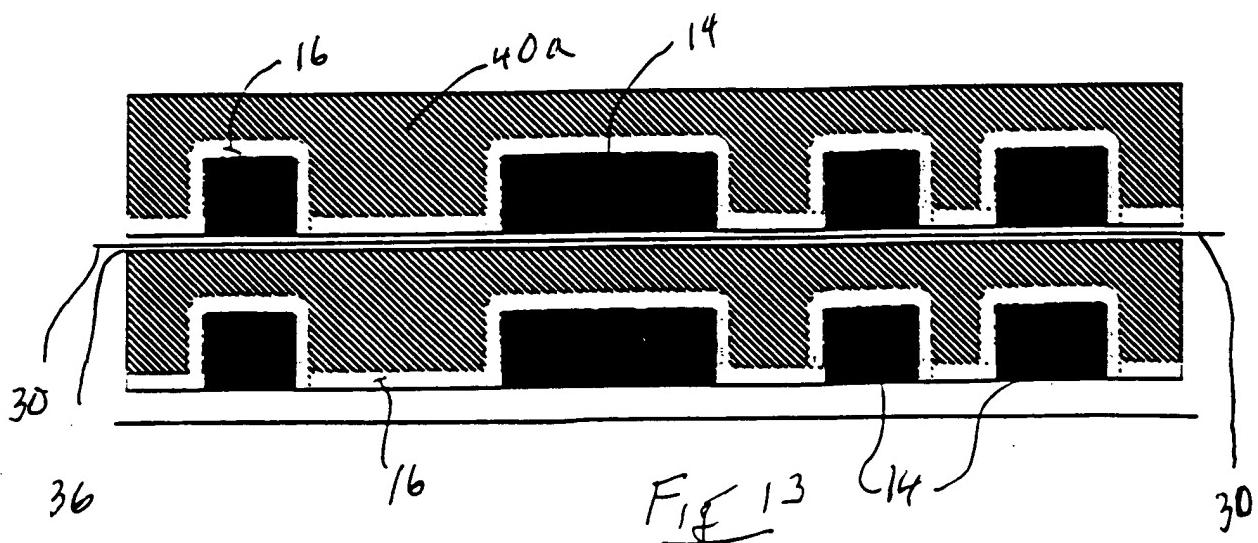
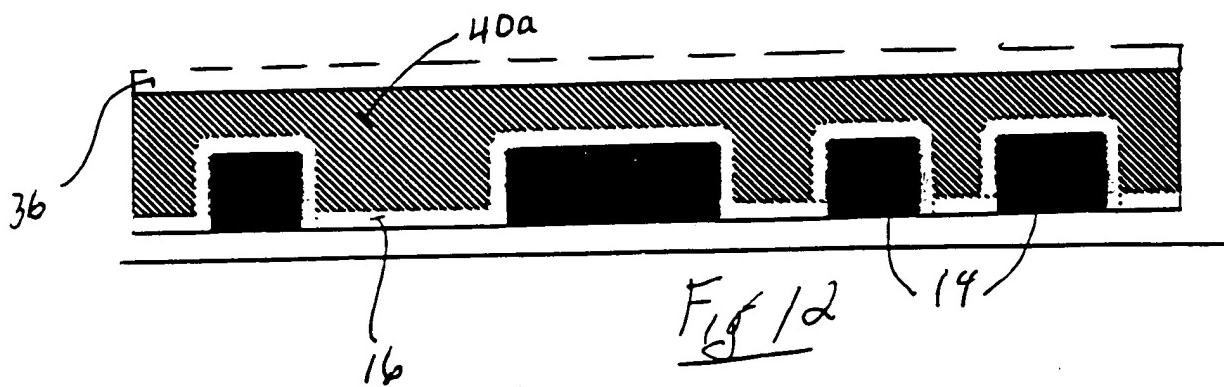
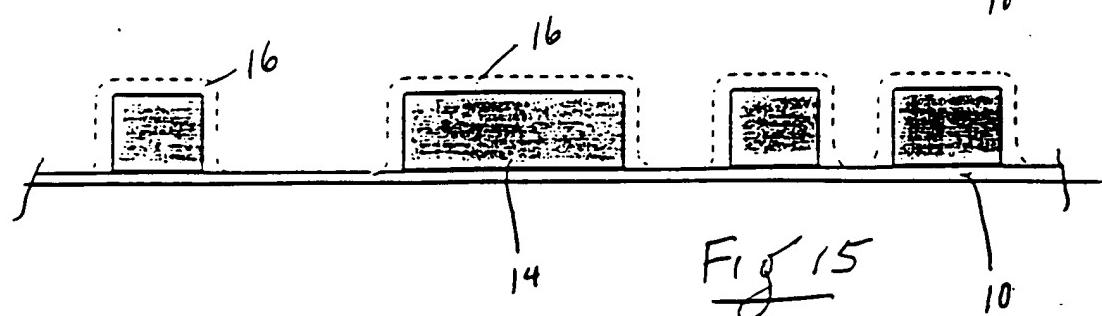
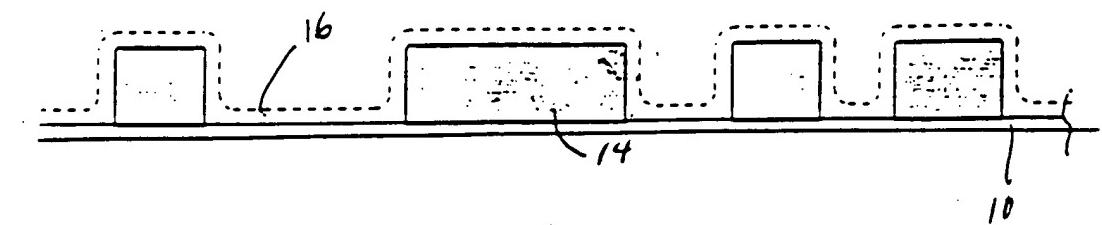
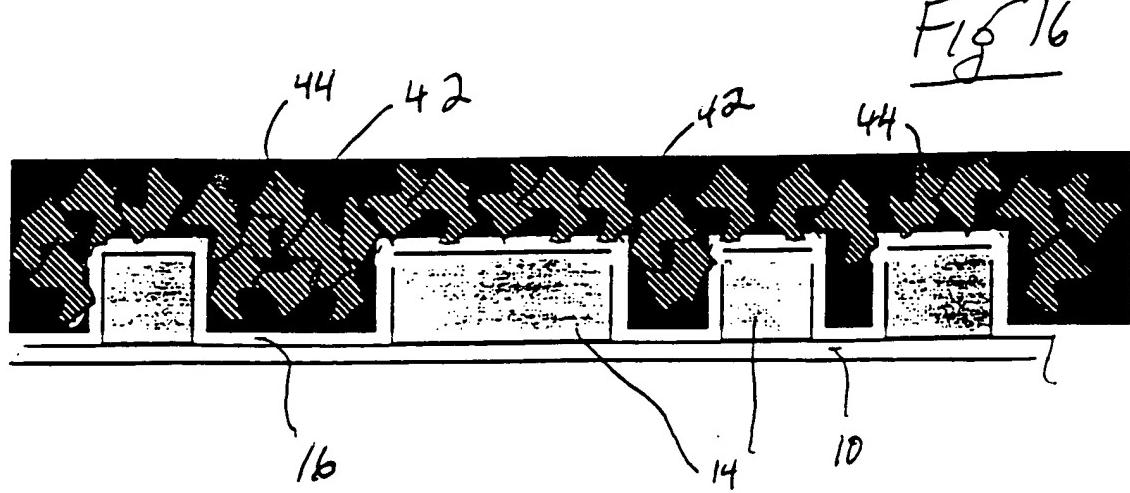


Fig 14Fig 15

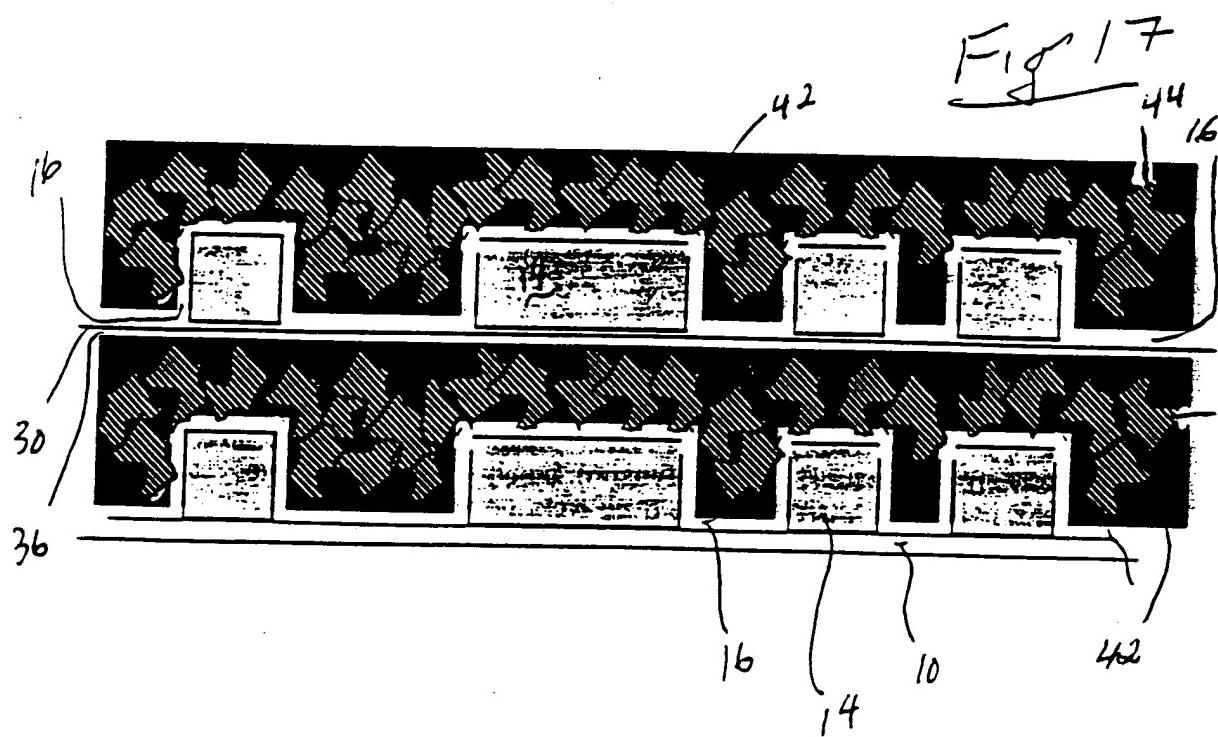
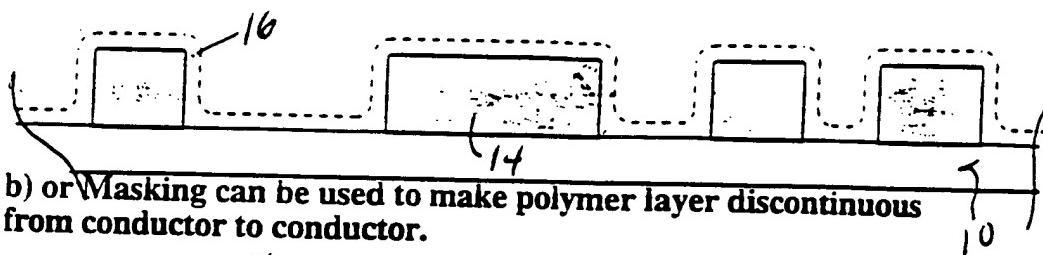


Fig 18

b) or Masking can be used to make polymer layer discontinuous from conductor to conductor.

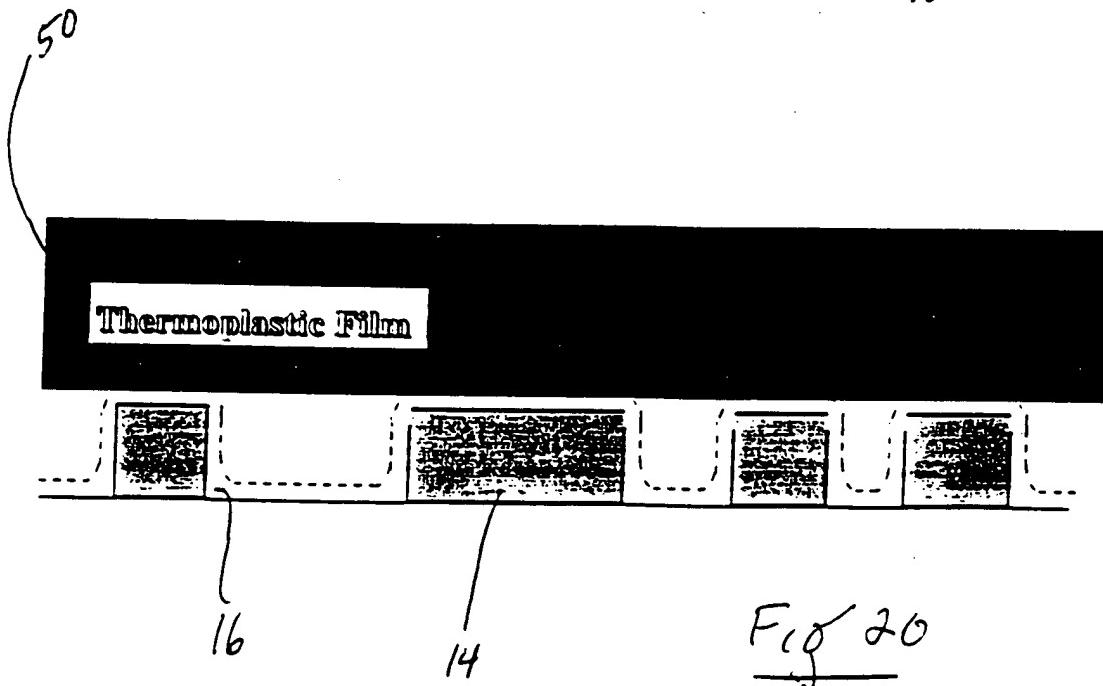
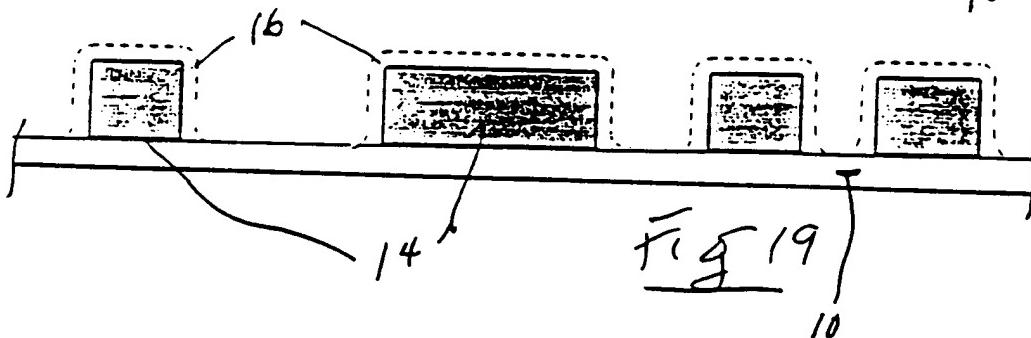
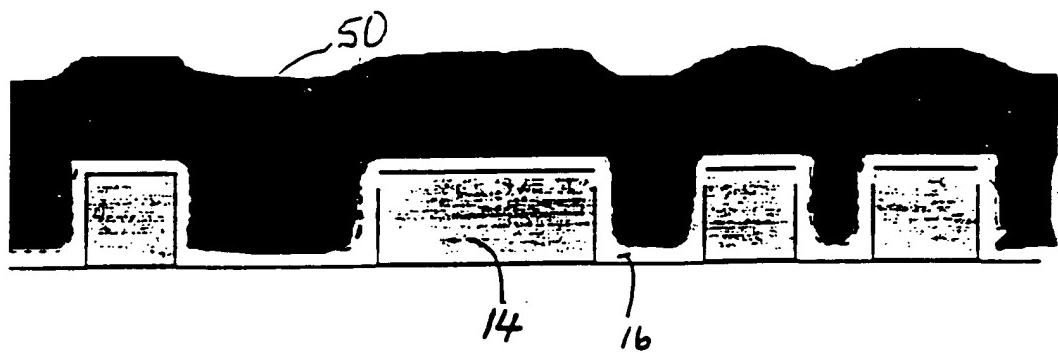
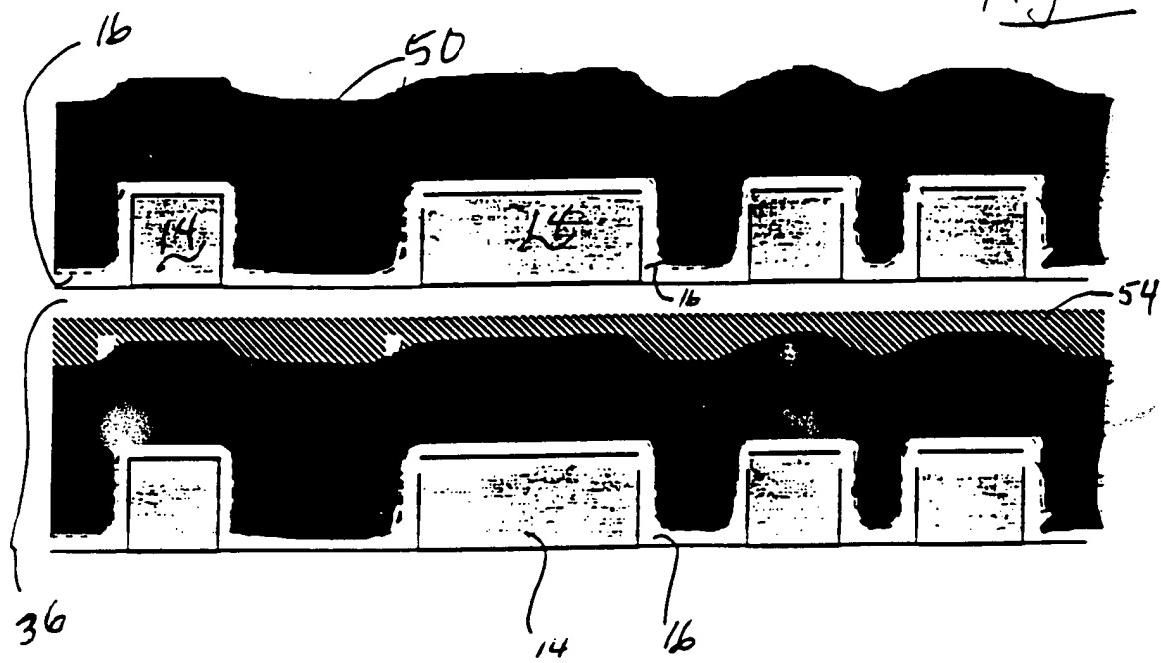
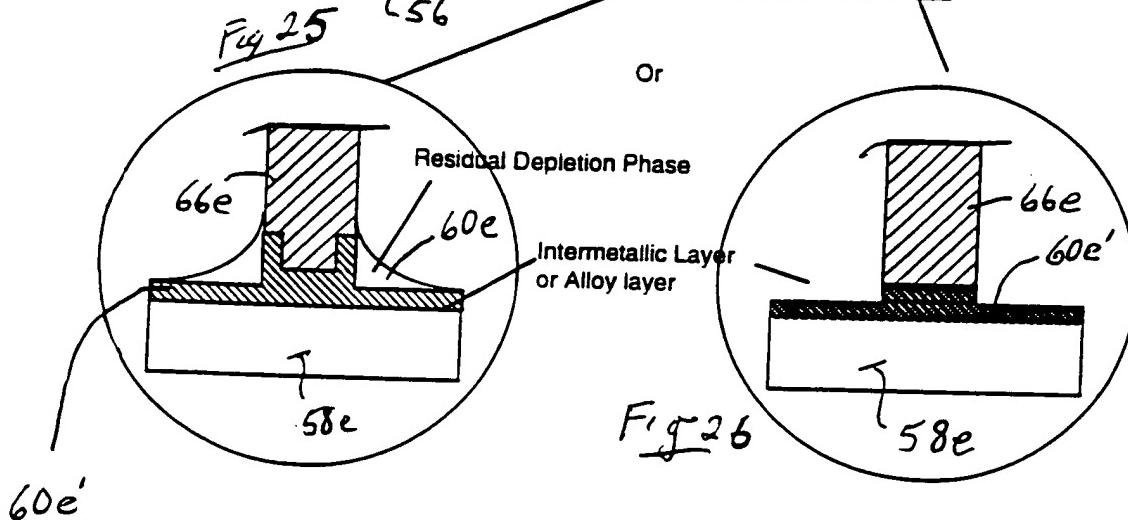
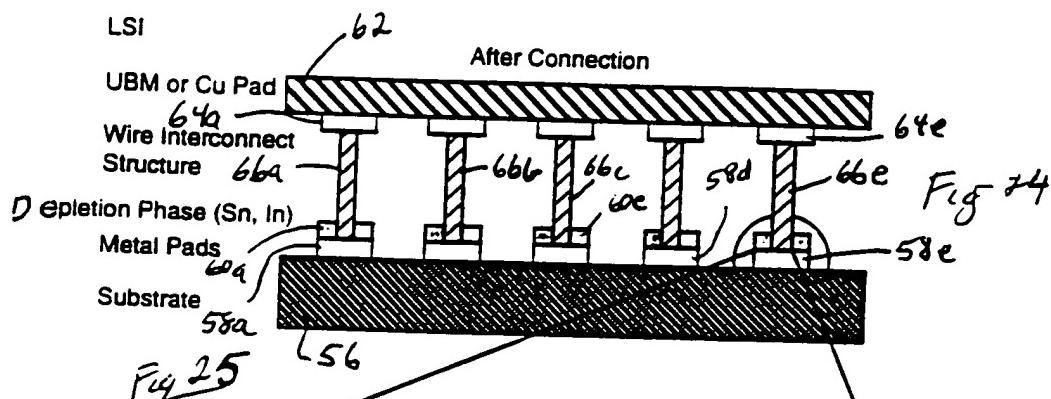
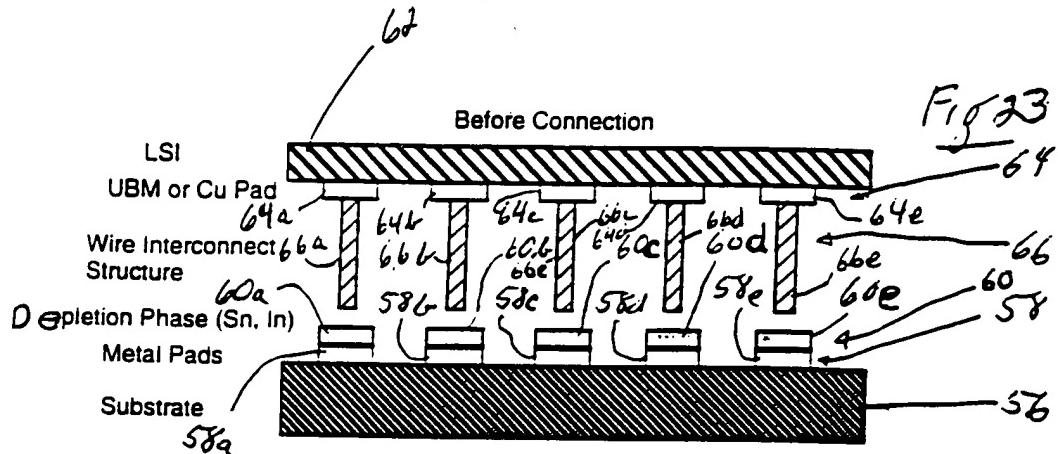
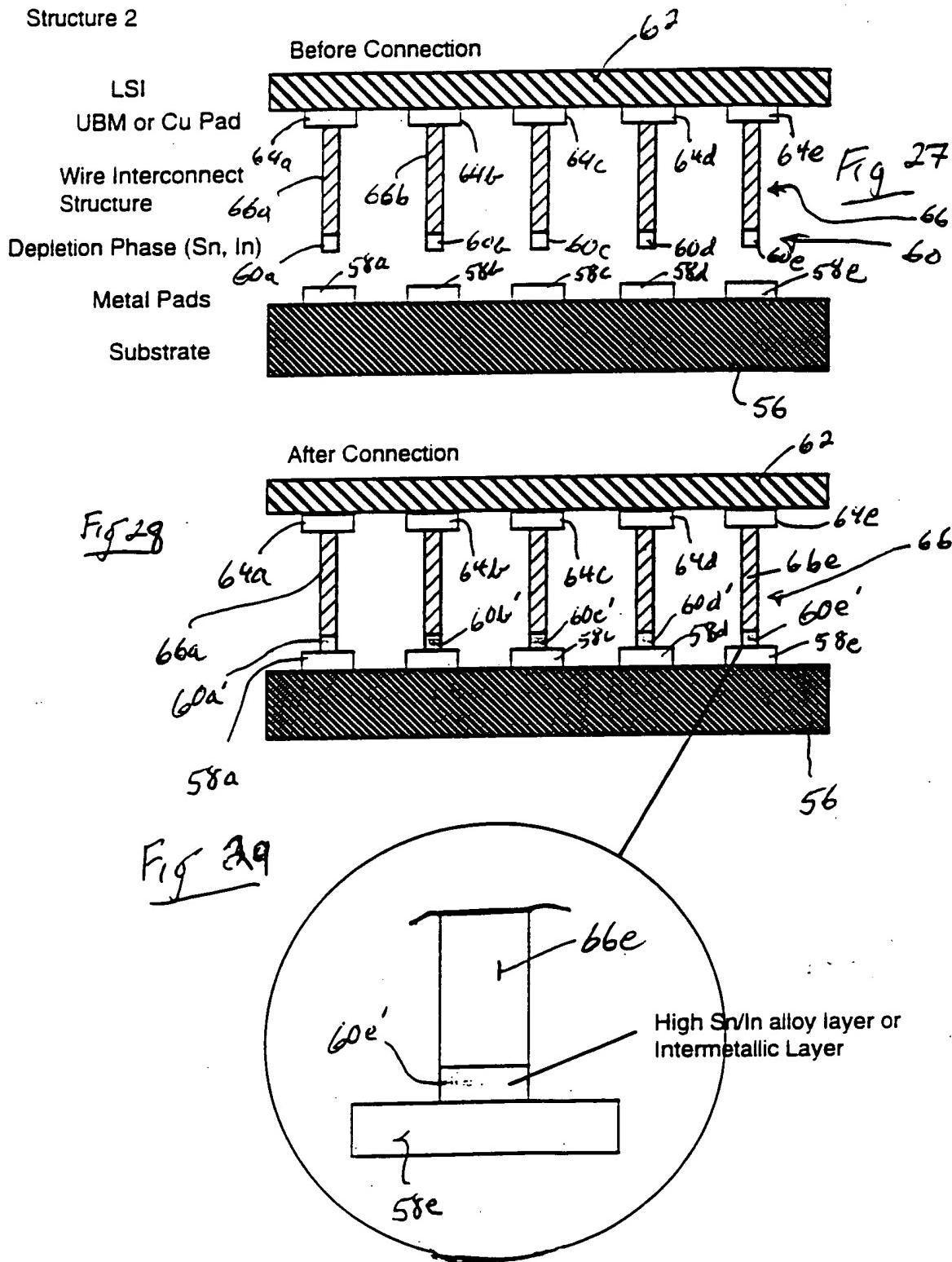
Fig 19Fig 20

Fig 21Fig 22

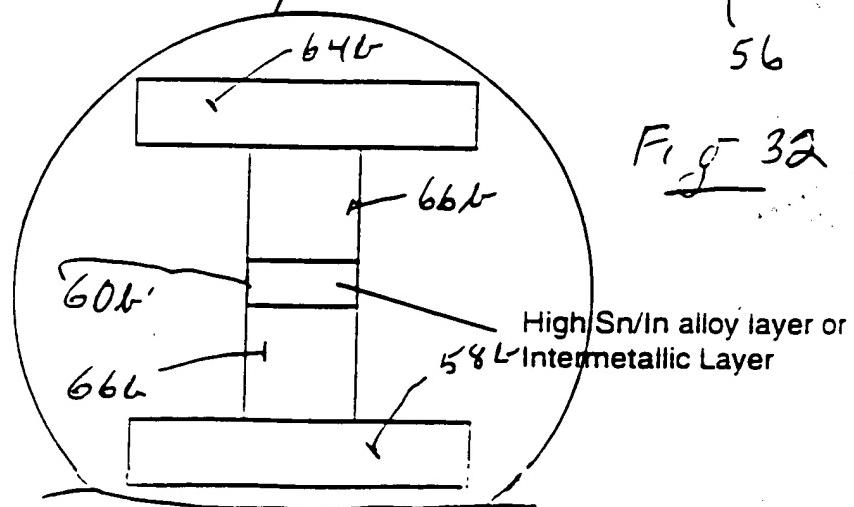
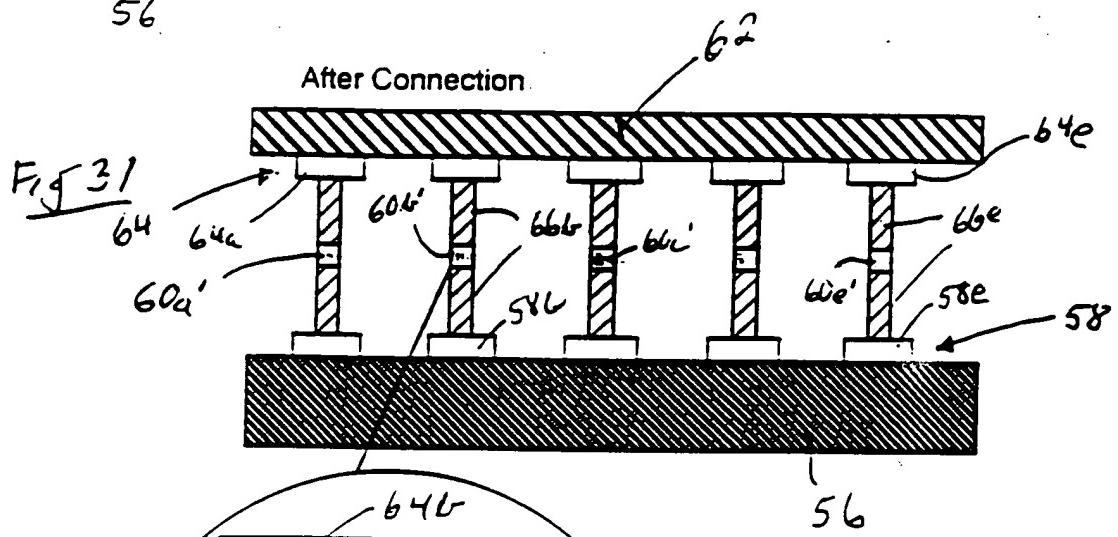
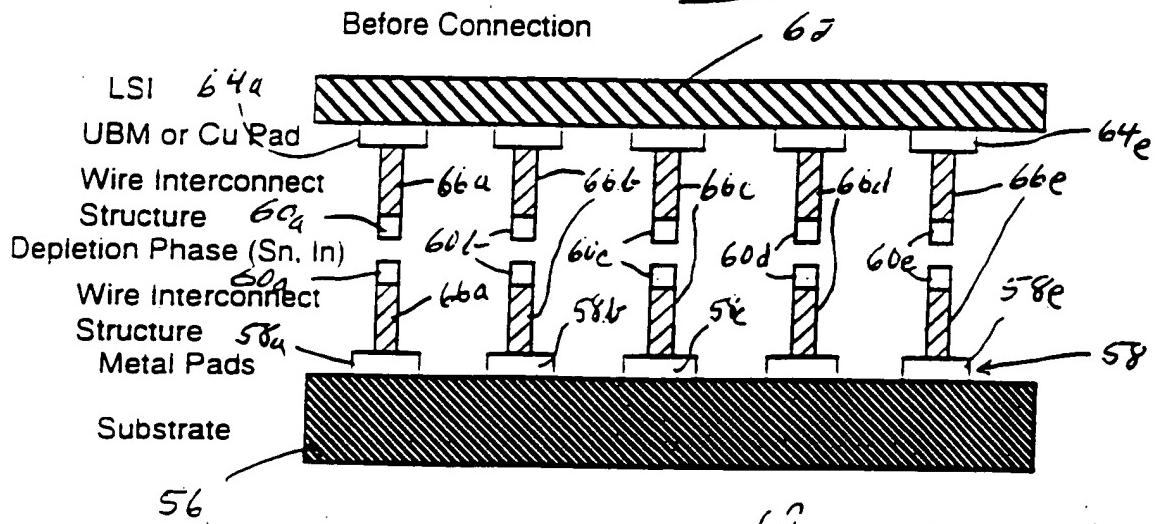


Structure 2

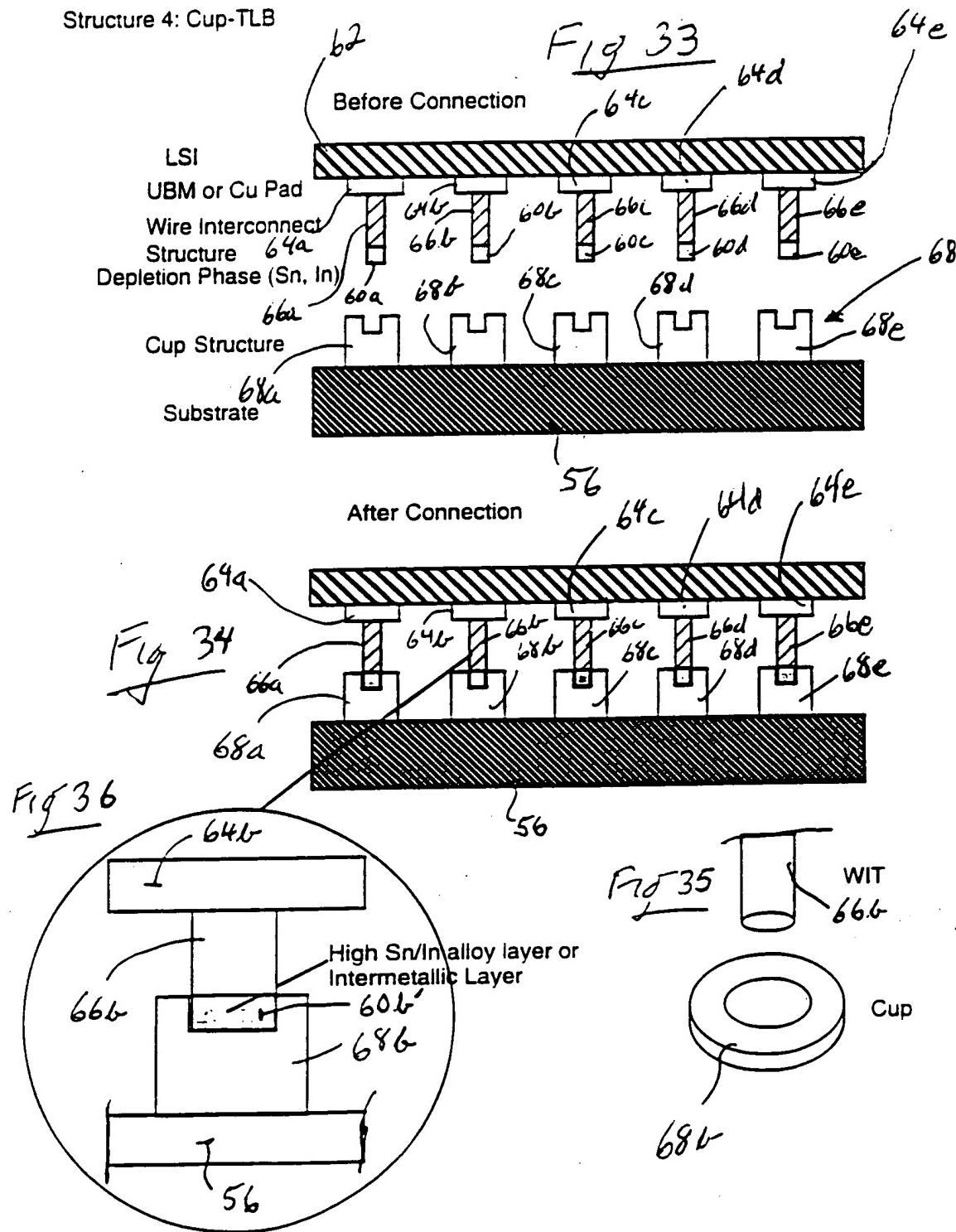


## Structure 3

Fig 30



Structure 4: Cup-TLB



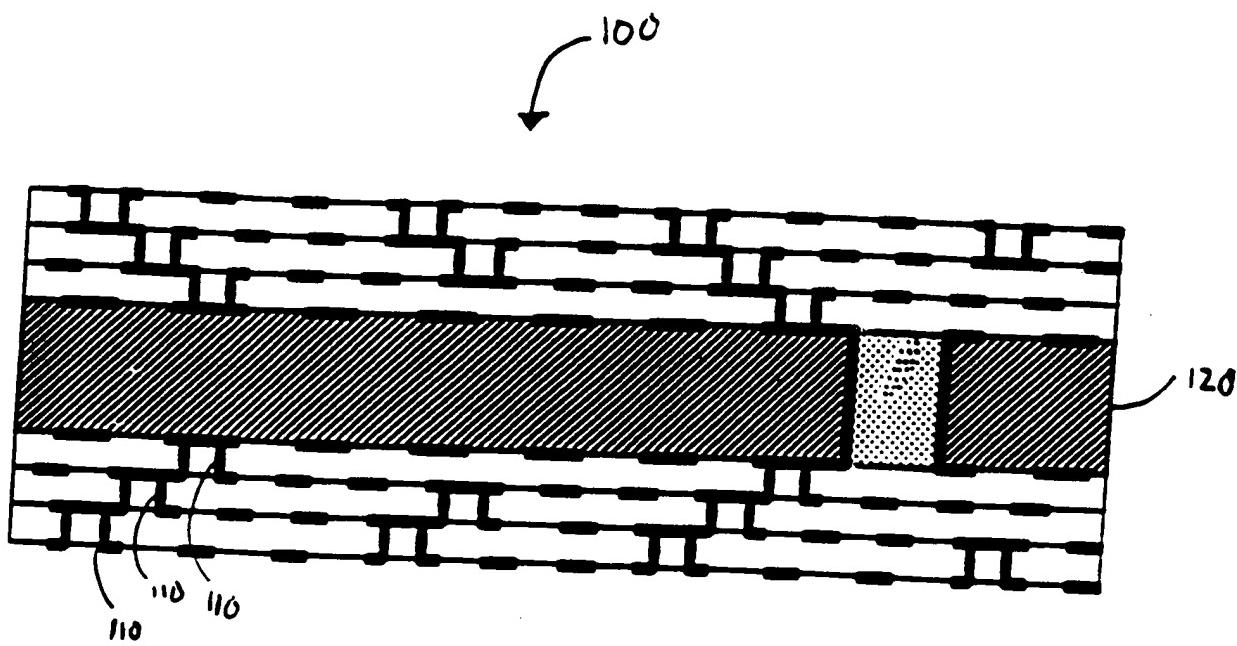
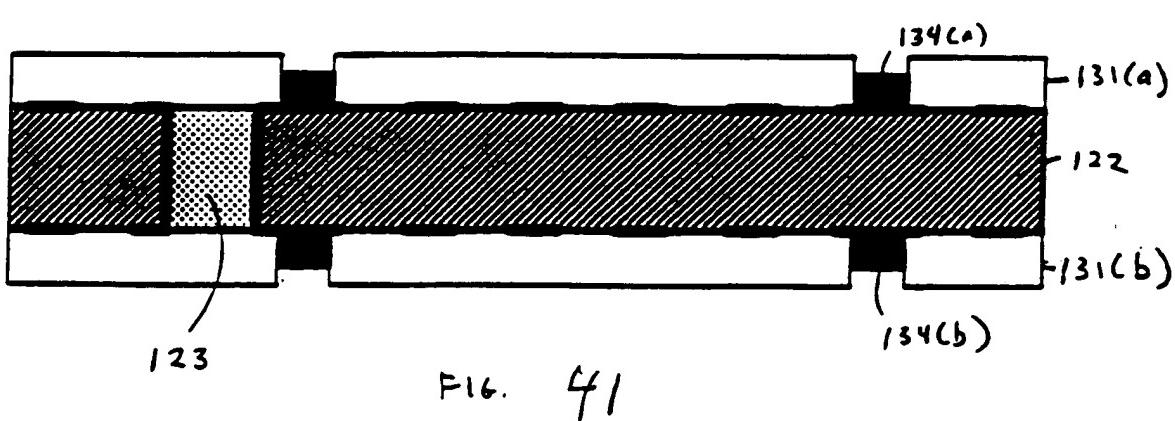
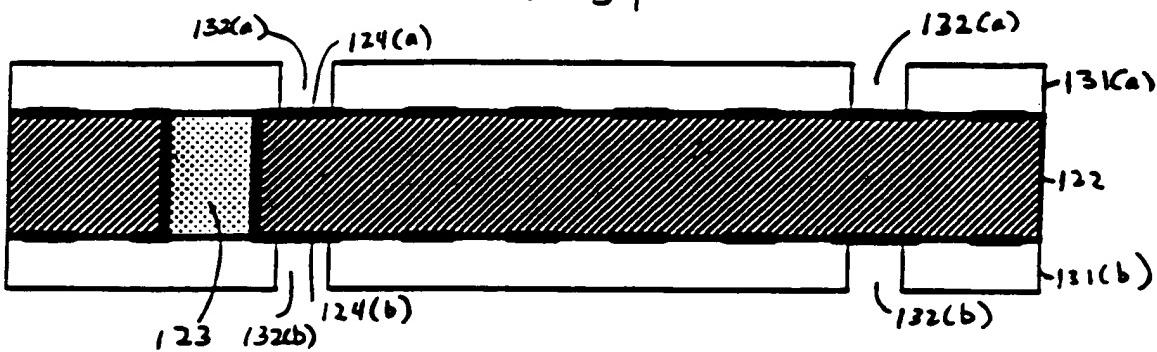
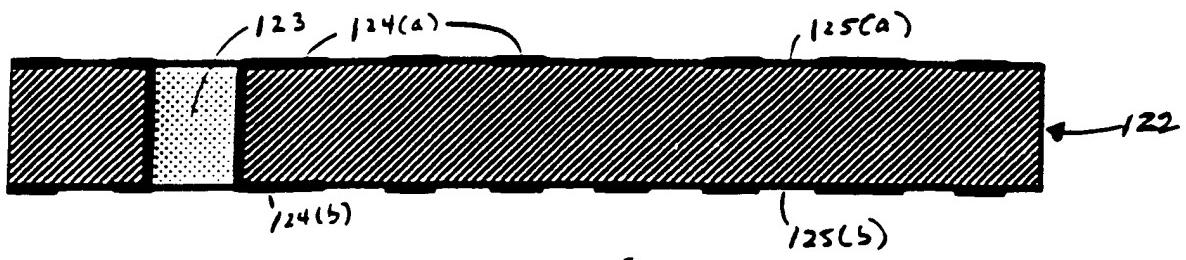
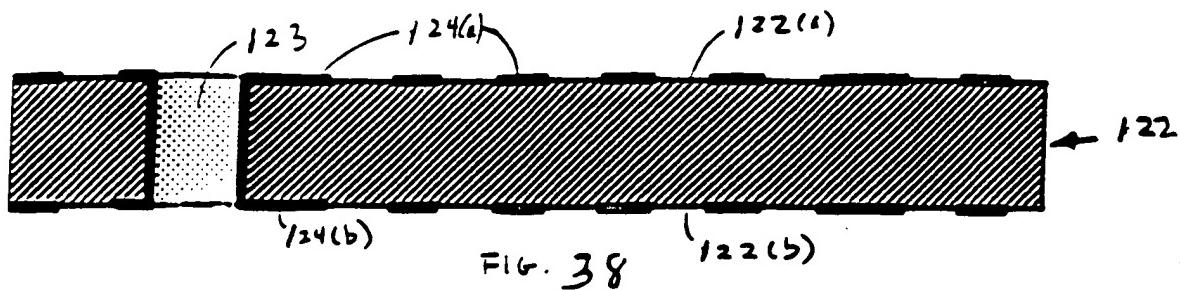


FIG. 37



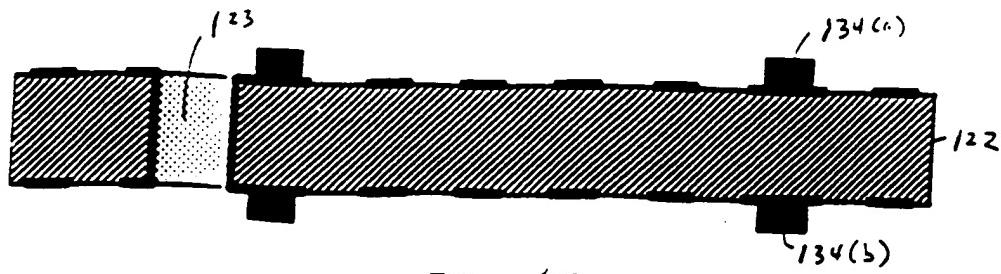


FIG. 42

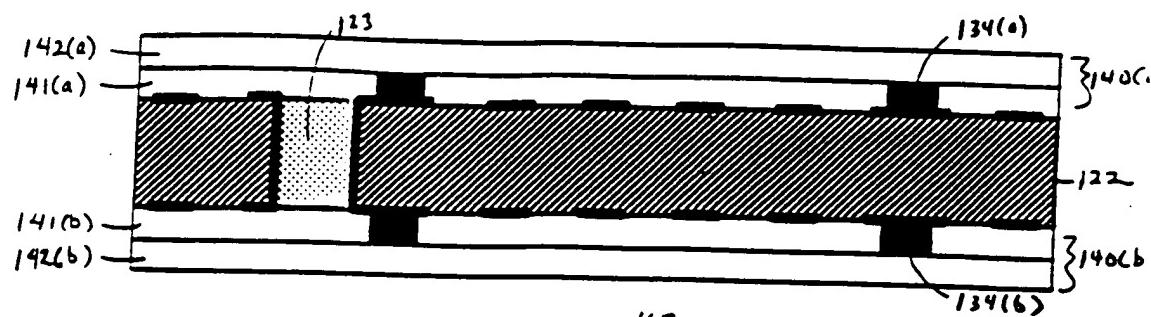


FIG. 43

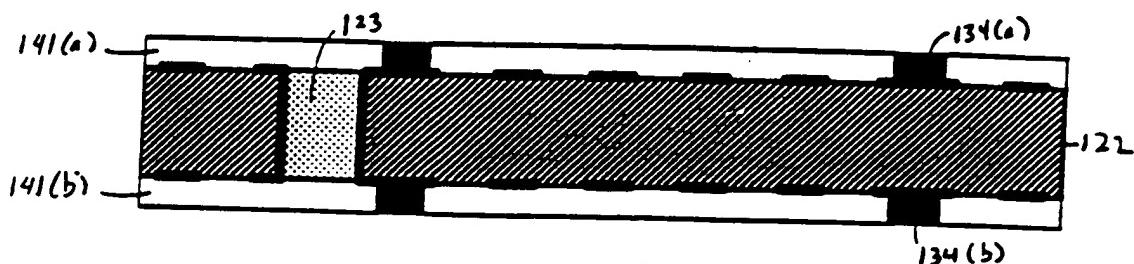


FIG. 44

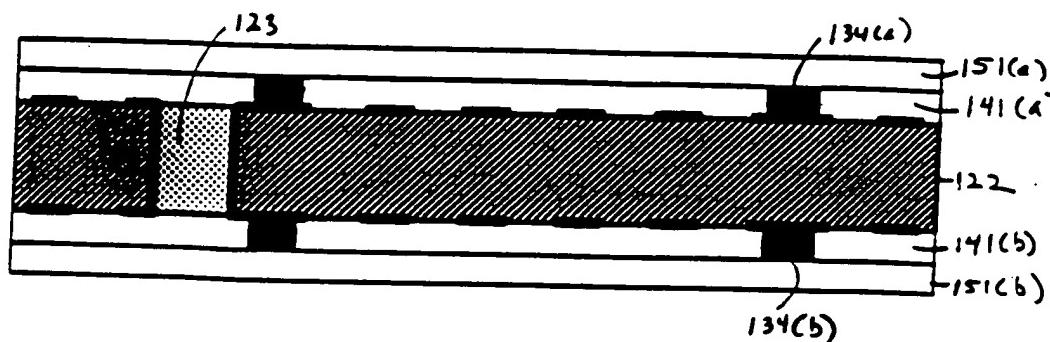
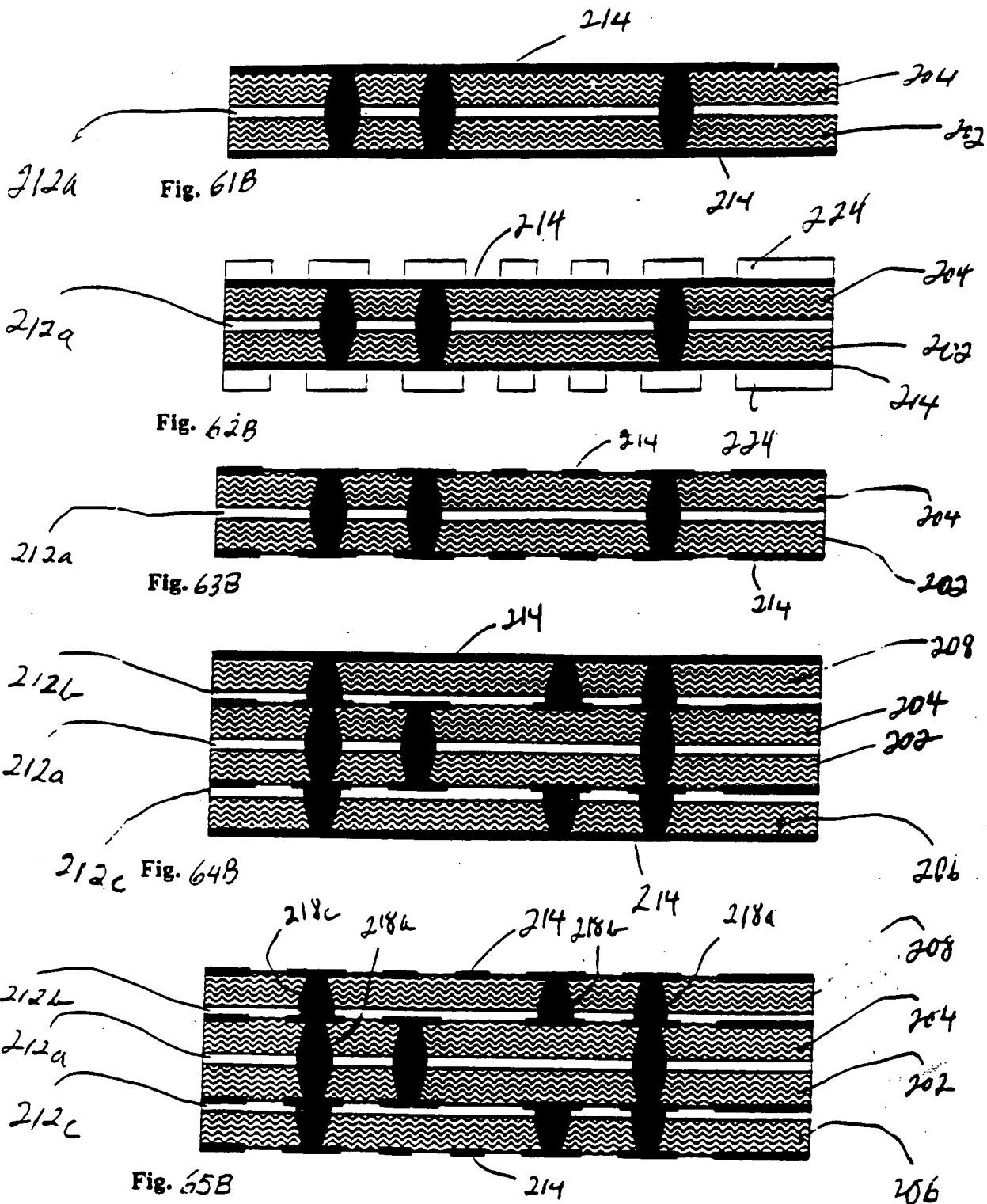
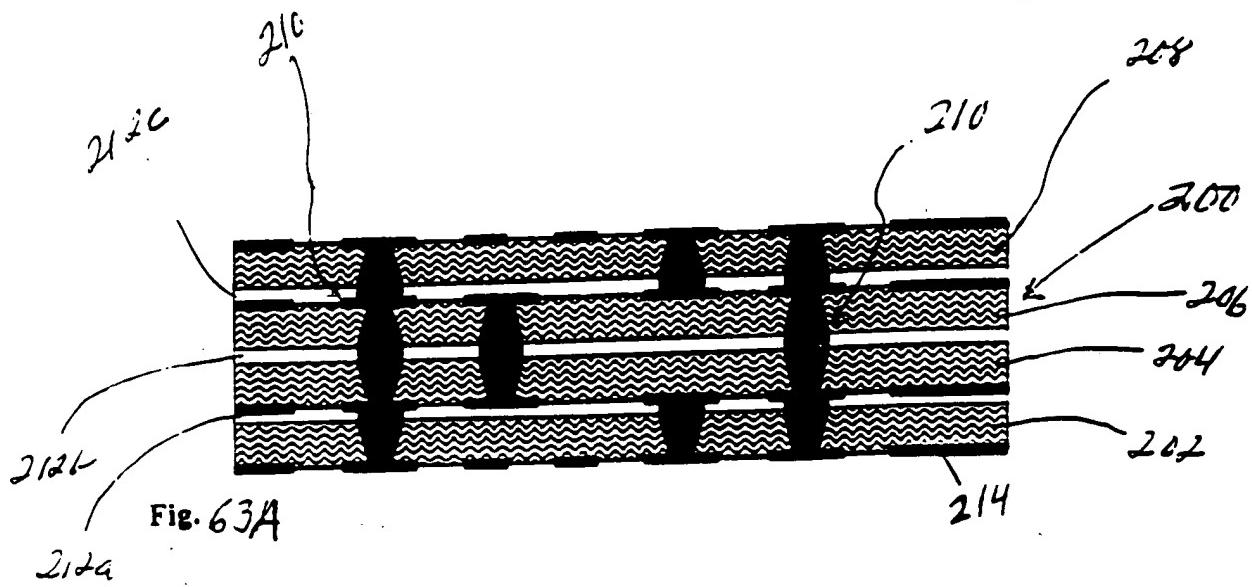
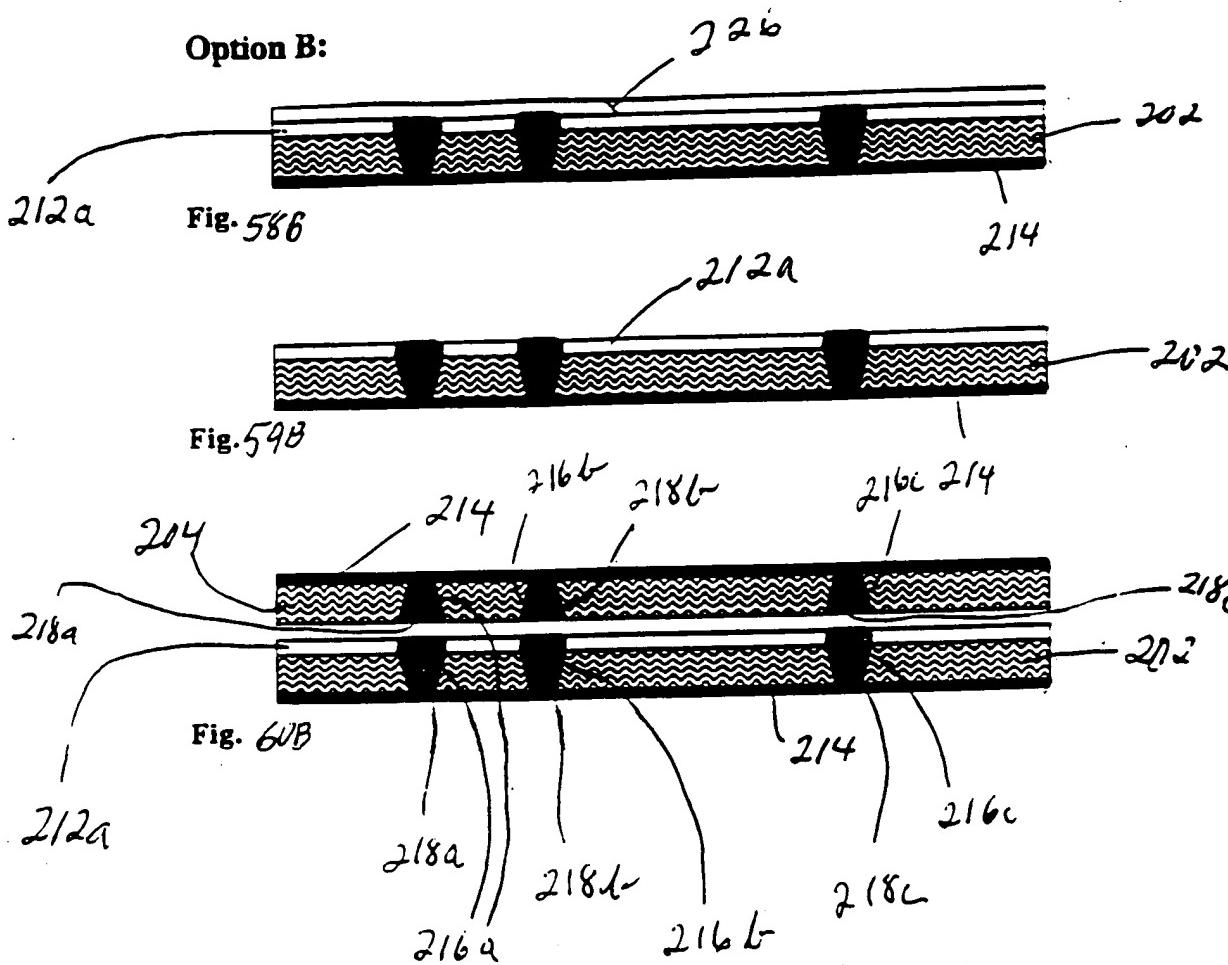


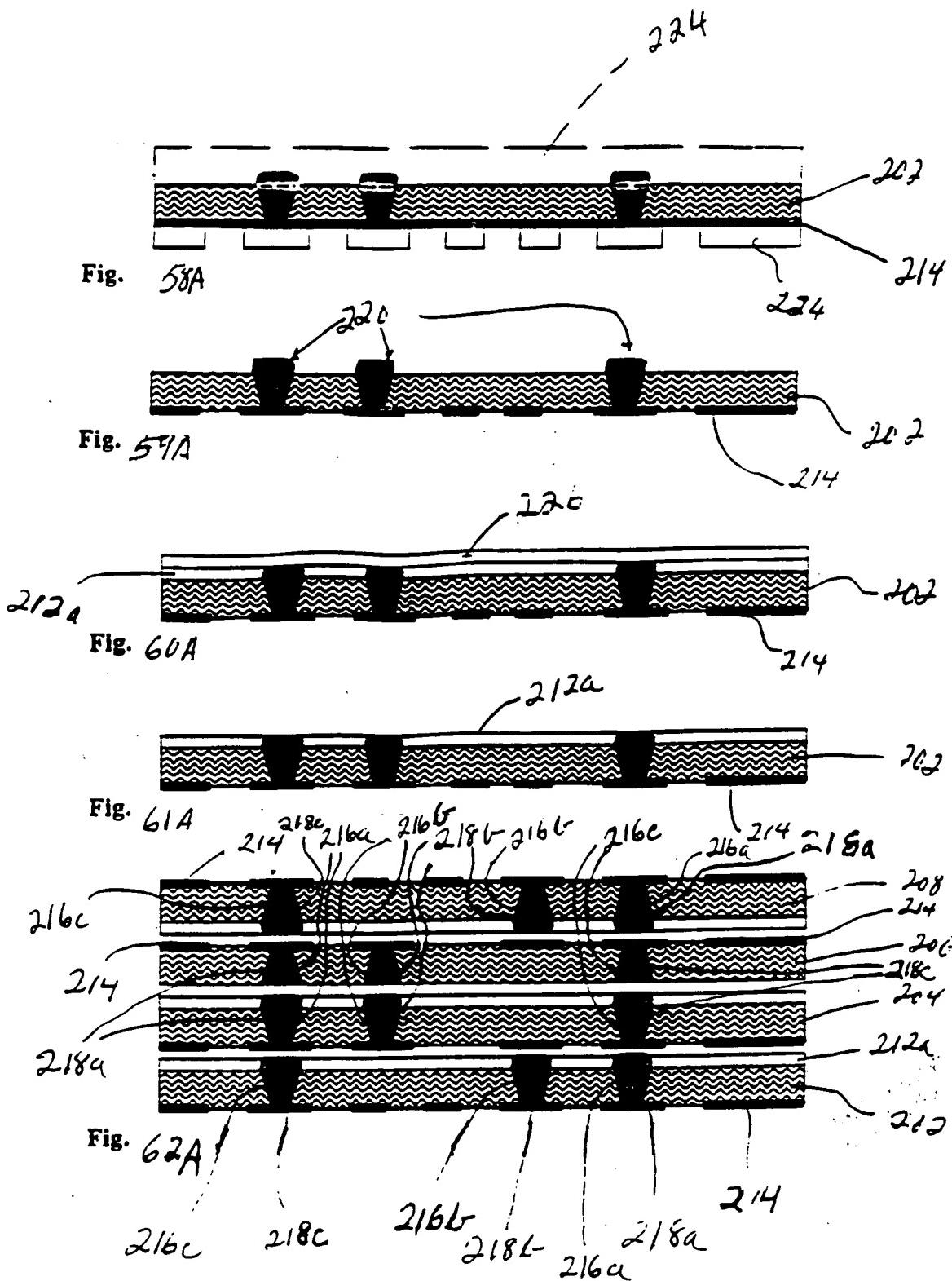
FIG. 45

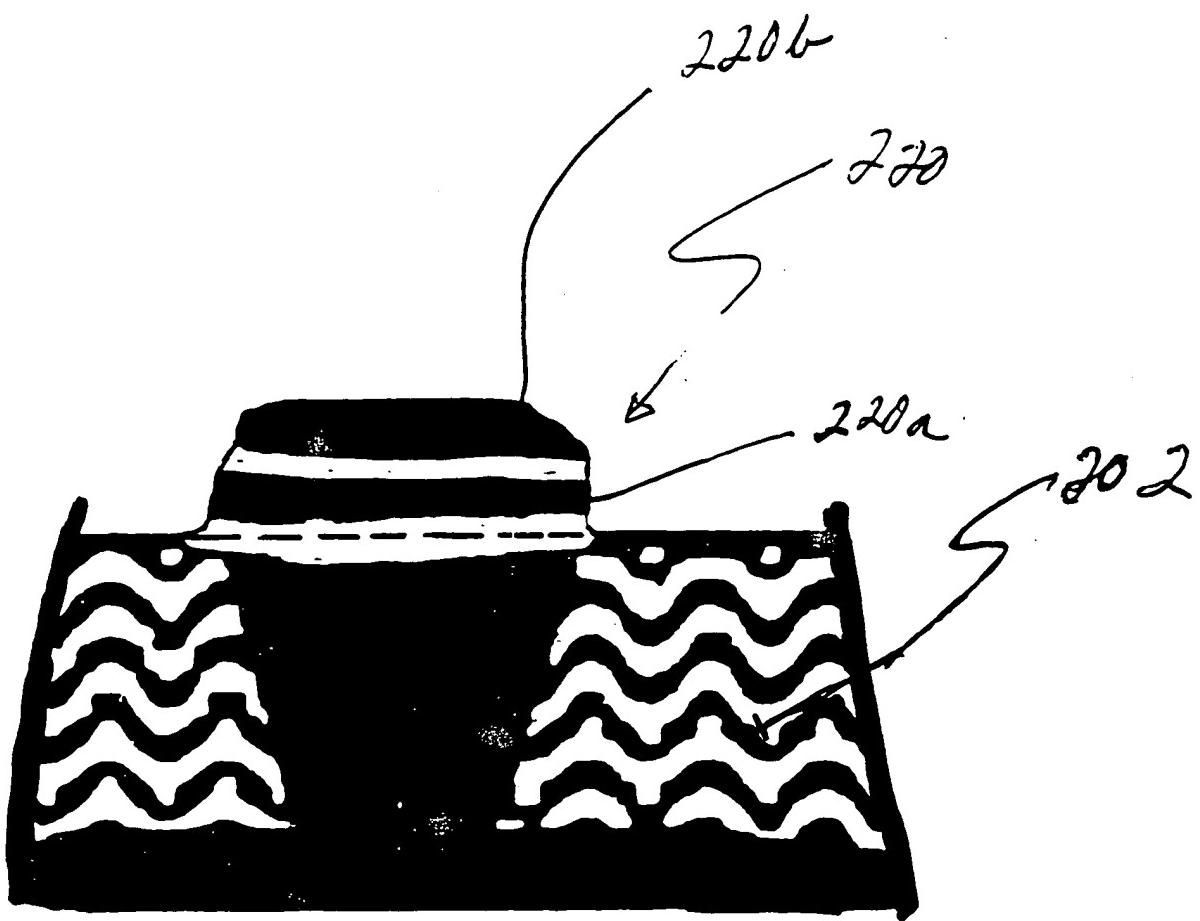




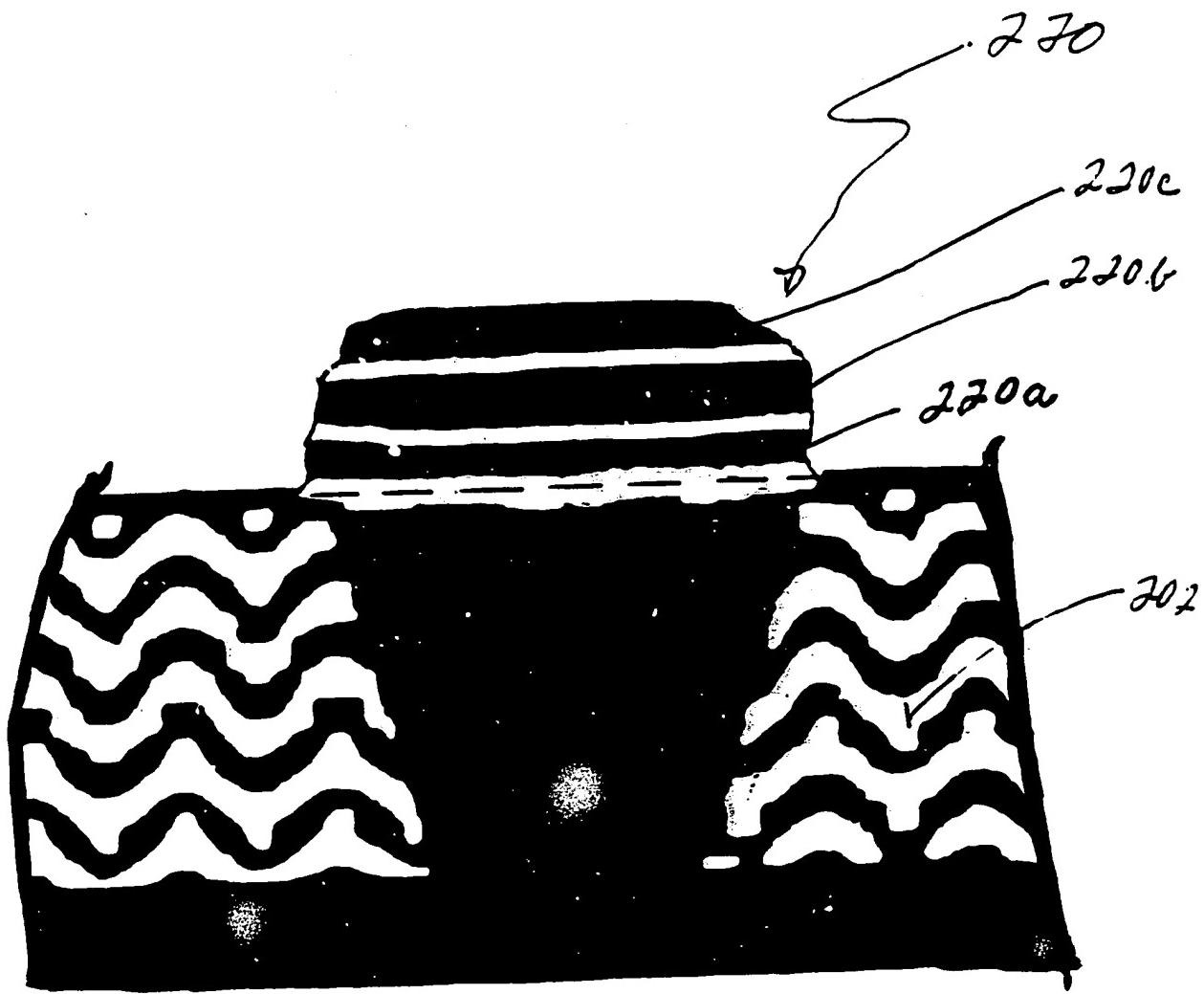
Option B:







57 C



573

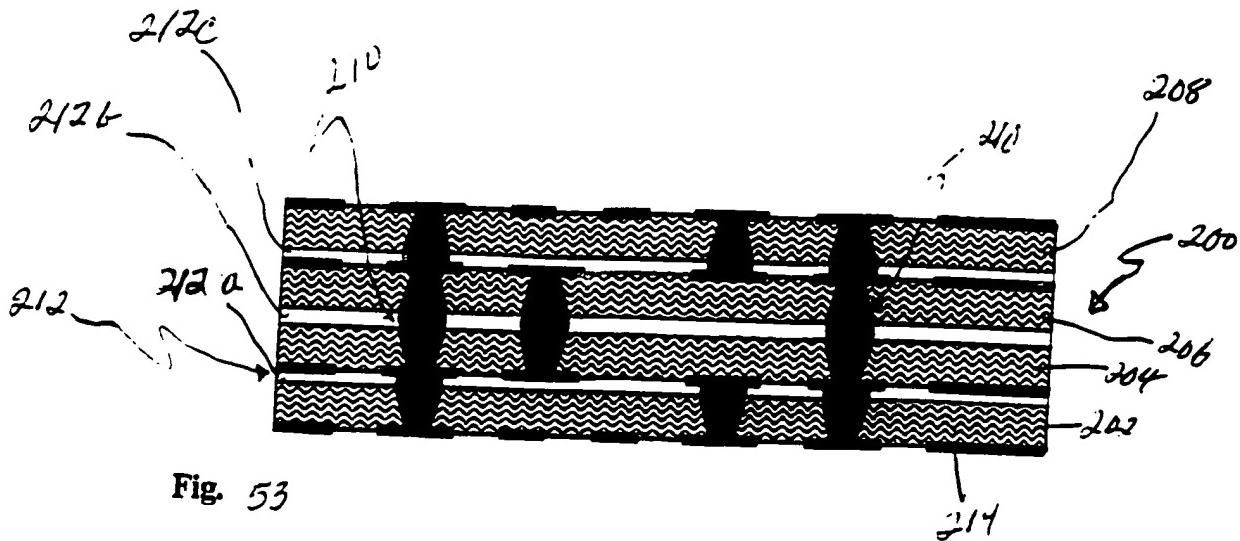


Fig. 53

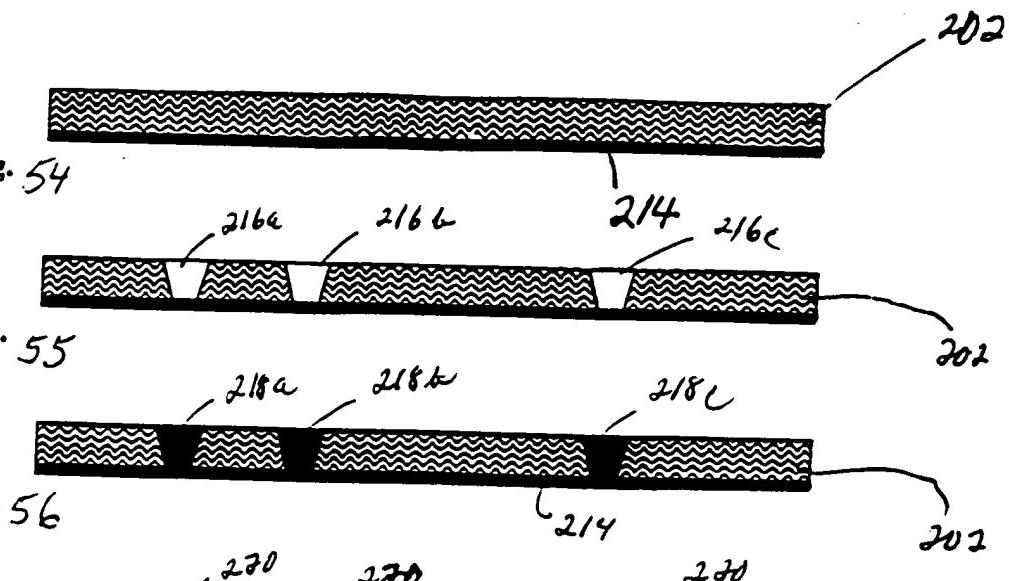
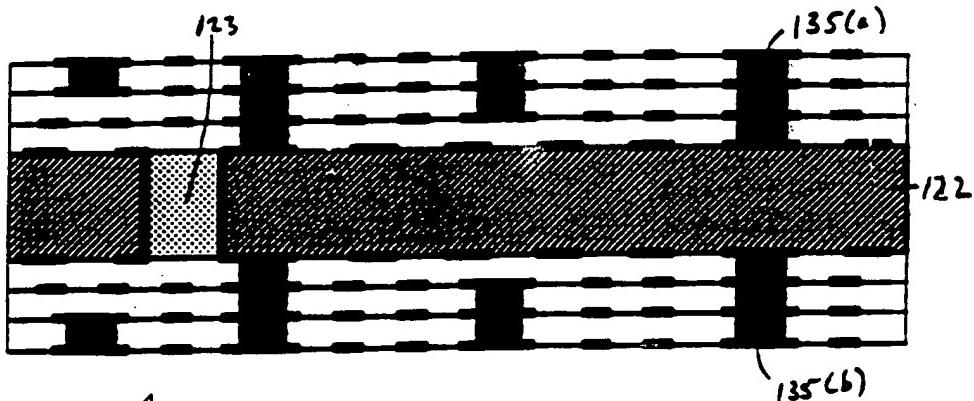
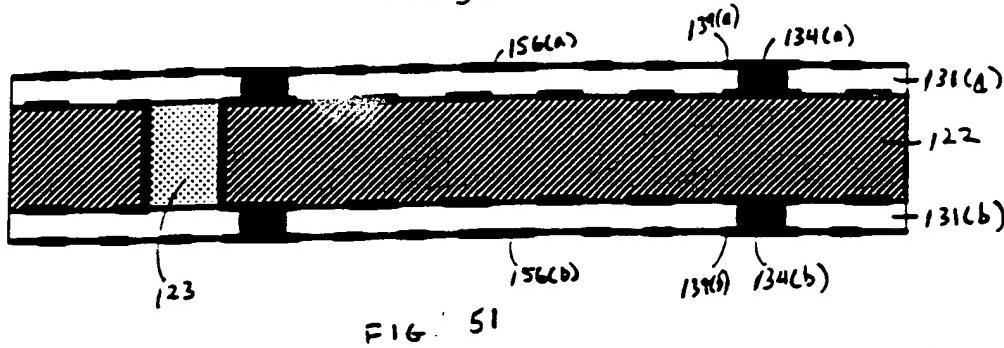
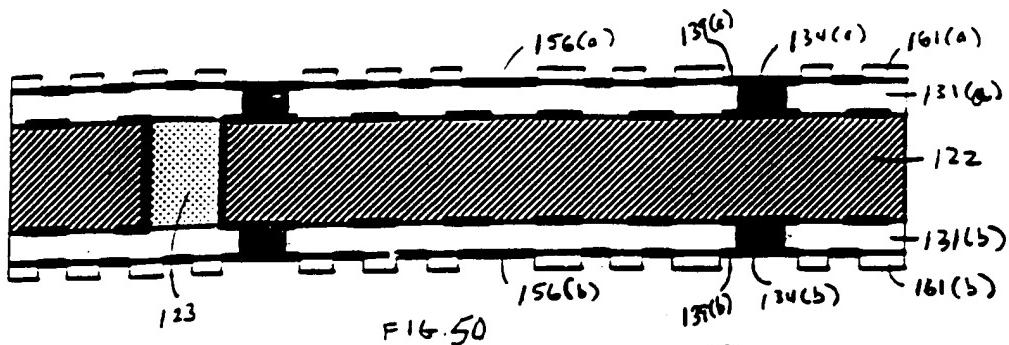


Fig. 54

Fig. 55

Fig. 56

Fig. 57A



170

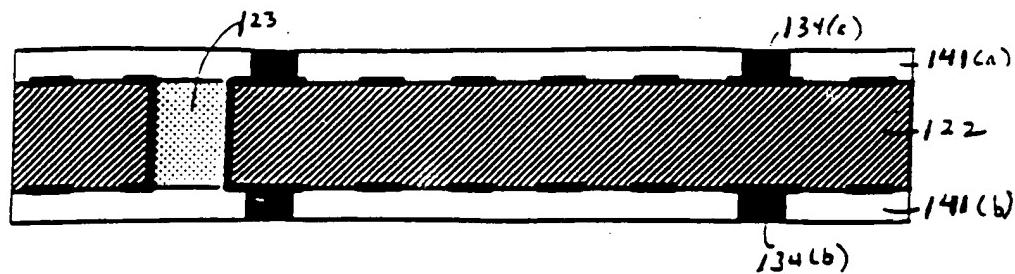


FIG. 47

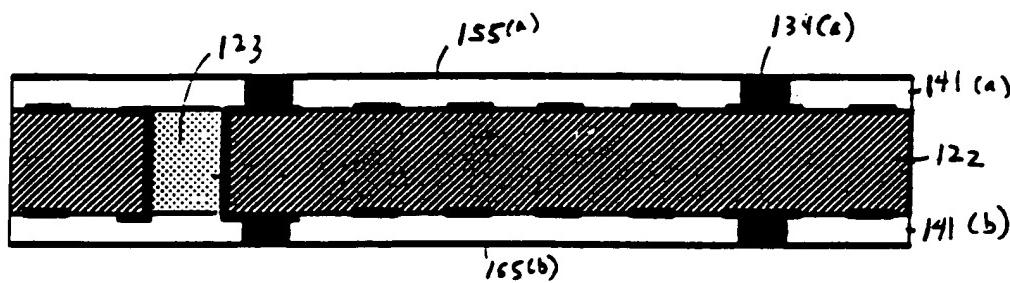


FIG. 48

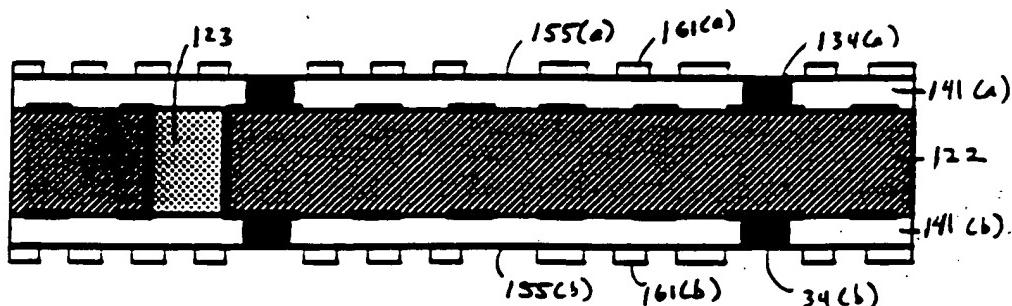


FIG. 49

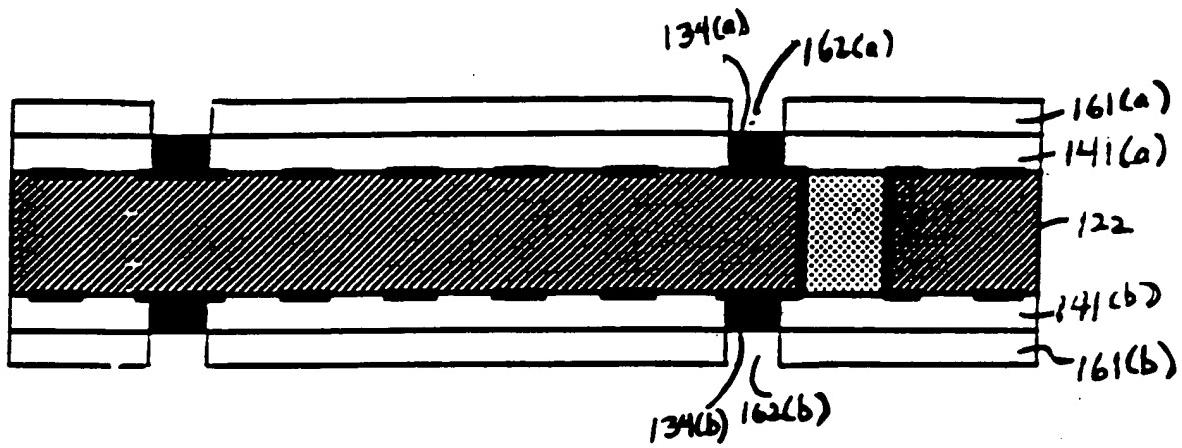


FIG. 46.